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June 2010

## FDB045AN08A0\_F085

## N-Channel PowerTrench<sup>®</sup> MOSFET 75V, 80A, $4.5m\Omega$

#### **Features**

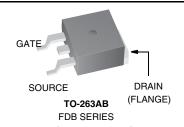
- $r_{DS(ON)} = 3.9 \text{m}\Omega$  (Typ.),  $V_{GS} = 10 \text{V}$ ,  $I_D = 80 \text{A}$
- $Q_g(tot) = 92nC (Typ.), V_{GS} = 10V$
- Low Miller Charge
- Low Q<sub>RR</sub> Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- Qualified to AEC Q101
- · RoHS Compliant

Formerly developmental type 82684



## **Applications**

- 42V Automotive Load Control
- · Starter / Alternator Systems
- · Electronic Power Steering Systems
- · Electronic Valve Train Systems
- DC-DC converters and Off-line UPS
- Distributed Power Architectures and VRMs
- · Primary Switch for 24V and 48V systems





## MOSFET Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

| Symbol            | Parameter                                                                                                                                                         | Ratings         | Units   |
|-------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------|---------|
| $V_{DSS}$         | Drain to Source Voltage                                                                                                                                           | 75              | V       |
| $V_{GS}$          | Gate to Source Voltage                                                                                                                                            | ±20             | V       |
| I <sub>D</sub>    | Drain Current Continuous ( $T_C < 137^{\circ}C$ , $V_{GS} = 10V$ ) Continuous ( $T_{amb} = 25^{\circ}C$ , $V_{GS} = 10V$ , with $R_{\theta JA} = 43^{\circ}C/W$ ) | 90<br>19        | A<br>A  |
| E <sub>AS</sub>   | Pulsed Single Pulse Avalanche Energy (Note 1)                                                                                                                     | Figure 4<br>600 | A<br>mJ |
|                   | Power dissipation                                                                                                                                                 | 310             | W       |
| $P_{D}$           | Derate above 25°C                                                                                                                                                 | 2.0             | W/°C    |
| $T_J$ , $T_{STG}$ | Operating and Storage Temperature                                                                                                                                 | -55 to 175      | °C      |

## **Thermal Characteristics**

| $R_{\theta JC}$ | Thermal Resistance Junction to Case TO-263                                      | 0.48 | °C/W |
|-----------------|---------------------------------------------------------------------------------|------|------|
| $R_{\theta JA}$ | Thermal Resistance Junction to Ambient TO-263 (Note 2)                          | 62   | °C/W |
| $R_{\theta JA}$ | Thermal Resistance Junction to Ambient TO-263, 1in <sup>2</sup> copper pad area | 43   | °C/W |

This product has been designed to meet the extreme test conditions and environment demanded by the automotive industry. For a copy of the requirements, see AEC Q101 at: http://www.aecouncil.com/

Reliability data can be found at: http://www.fairchildsemi.com/products/discrete/reliability/index.html.

All Fairchild Semiconductor products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.

## **Package Marking and Ordering Information**

| <b>Device Marking</b> | Device            | Package  | Reel Size | Tape Width | Quantity  |
|-----------------------|-------------------|----------|-----------|------------|-----------|
| FDB045AN08A0          | FDB045AN08A0_F085 | TO-263AB | 330mm     | 24mm       | 800 units |

## **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted

| Parameter                         | Test Co                                                                         | onditions                        | Min | Тур | Max         | Units       |
|-----------------------------------|---------------------------------------------------------------------------------|----------------------------------|-----|-----|-------------|-------------|
| acteristics                       |                                                                                 |                                  |     |     |             |             |
| Drain to Source Breakdown Voltage | $I_D = 250 \mu A, V_C$                                                          | <sub>GS</sub> = 0V               | 75  | -   | -           | V           |
| Zoro Cato Voltago Drain Current   | $V_{DS} = 60V$                                                                  |                                  | -   | -   | 1           | ^           |
| Zero Gate Voltage Drain Current   | $V_{GS} = 0V$                                                                   | $T_{\rm C} = 150^{\rm o}{\rm C}$ | -   |     | 250         | μΑ          |
| Gate to Source Leakage Current    | $V_{GS} = \pm 20V$                                                              |                                  | -   | -   | ±100        | nA          |
|                                   | acteristics  Drain to Source Breakdown Voltage  Zero Gate Voltage Drain Current |                                  |     |     | acteristics | acteristics |

#### **On Characteristics**

| V <sub>GS(TH)</sub> | Gate to Source Threshold Voltage | $V_{GS} = V_{DS}, I_{D} = 250 \mu A$               | 2 | -      | 4      | V    |
|---------------------|----------------------------------|----------------------------------------------------|---|--------|--------|------|
|                     |                                  | $I_D = 80A, V_{GS} = 10V$                          | - | 0.0039 | 0.0045 |      |
| r <sub>DS(ON)</sub> | Drain to Source On Resistance    | $I_D = 37A, V_{GS} = 6V$                           | - | 0.0056 | 0.0084 | 0    |
|                     |                                  | $I_D = 80A, V_{GS} = 10V,$<br>$T_J = 175^{\circ}C$ | - | 0.008  | 0.011  | - 52 |

## **Dynamic Characteristics**

| C <sub>ISS</sub> | Input Capacitance                | V 05V V 0V                                               | - | 6600 | -   | pF |
|------------------|----------------------------------|----------------------------------------------------------|---|------|-----|----|
| C <sub>OSS</sub> | Output Capacitance               | V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V,<br>f = 1MHz | - | 1000 | -   | pF |
| C <sub>RSS</sub> | Reverse Transfer Capacitance     | 1 - 1101112                                              | - | 240  | -   | pF |
| $Q_{g(TOT)}$     | Total Gate Charge at 10V         | V <sub>GS</sub> = 0V to 10V                              |   | 92   | 138 | nC |
| $Q_{g(TH)}$      | Threshold Gate Charge            | $V_{GS} = 0V \text{ to } 2V$ $V_{DD} = 40V$              | - | 11   | 17  | nC |
| $Q_{gs}$         | Gate to Source Gate Charge       | I <sub>D</sub> = 80A                                     | - | 27   | -   | nC |
| Q <sub>gs2</sub> | Gate Charge Threshold to Plateau | $I_g = 1.0 \text{mA}$                                    | - | 16   | -   | nC |
| $Q_{gd}$         | Gate to Drain "Miller" Charge    |                                                          | - | 21   | -   | nC |

## **Switching Characteristics** (V<sub>GS</sub> = 10V)

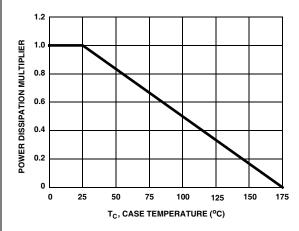
| t <sub>ON</sub>     | Turn-On Time        |                                    | - | -  | 160 | ns |
|---------------------|---------------------|------------------------------------|---|----|-----|----|
| t <sub>d(ON)</sub>  | Turn-On Delay Time  |                                    | - | 18 | -   | ns |
| t <sub>r</sub>      | Rise Time           | $V_{DD} = 40V, I_D = 80A$          | - | 88 | -   | ns |
| t <sub>d(OFF)</sub> | Turn-Off Delay Time | $V_{GS} = 10V, R_{GS} = 3.3\Omega$ | - | 40 | -   | ns |
| t <sub>f</sub>      | Fall Time           |                                    | - | 45 | -   | ns |
| t <sub>OFF</sub>    | Turn-Off Time       |                                    | - | -  | 128 | ns |

## **Drain-Source Diode Characteristics**

| V <sub>SD</sub> | Source to Drain Diode Voltage | I <sub>SD</sub> = 80A                      | - | - | 1.25 | V  |
|-----------------|-------------------------------|--------------------------------------------|---|---|------|----|
|                 |                               | I <sub>SD</sub> = 40A                      | - | - | 1.0  | V  |
| t <sub>rr</sub> | Reverse Recovery Time         | $I_{SD} = 75A$ , $dI_{SD}/dt = 100A/\mu s$ | - | - | 53   | ns |
| Q <sub>RR</sub> | Reverse Recovered Charge      | $I_{SD} = 75A$ , $dI_{SD}/dt = 100A/\mu s$ | - | - | 54   | nC |

Notes: 1: Starting  $T_J = 25^{\circ}C$ , L = 0.48mH,  $I_{AS} = 50$ A. 2: Pulse Width = 100s





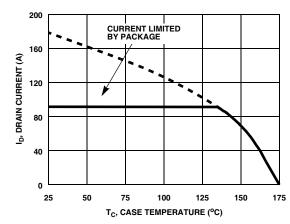


Figure 1. Normalized Power Dissipation vs Ambient Temperature

Figure 2. Maximum Continuous Drain Current vs Case Temperature

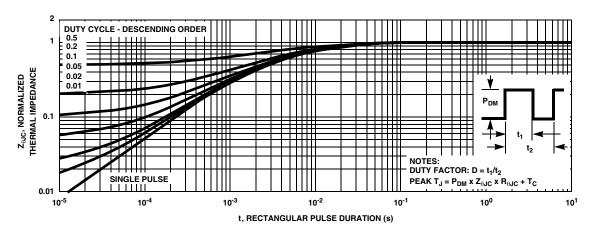


Figure 3. Normalized Maximum Transient Thermal Impedance

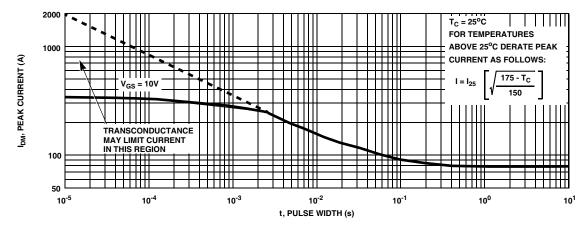
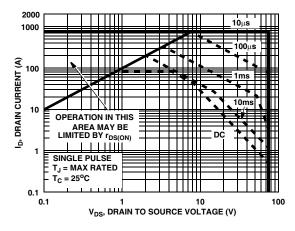


Figure 4. Peak Current Capability





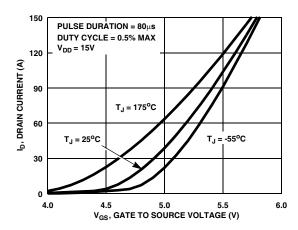
 $\begin{array}{c} 500 \\ \hline \\ \text{If R} = 0 \\ t_{AV} = (\text{L})(t_{AS})/(1.3^*\text{RATED BV}_{DSS} \cdot \text{V}_{DD}) \\ \hline \\ \text{If R} \neq 0 \\ t_{AV} = (\text{L/R})\ln[(t_{AS}*R)/(1.3^*\text{RATED BV}_{DSS} \cdot \text{V}_{DD}) + 1] \\ \hline \\ \text{STARTING T}_J = 150^\circ\text{C} \\ \hline \\ \text{STARTING T}_J = 150^\circ\text{C} \\ \hline \\ \text{1} \\ \text{0.01} \\ \hline \\ \text{0.1} \\ \text{1} \\ \text{0.01} \\ \hline \\ \text{100} \\ \hline \end{array}$ 

Figure 5. Forward Bias Safe Operating Area

NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching

Capability



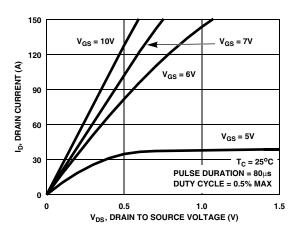
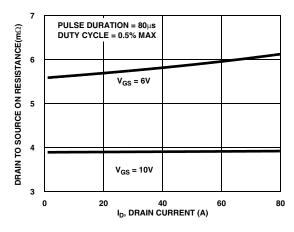


Figure 7. Transfer Characteristics

Figure 8. Saturation Characteristics



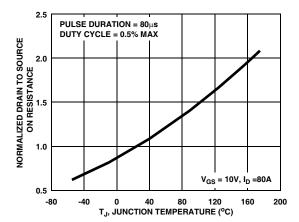


Figure 9. Drain to Source On Resistance vs Drain Current

Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

## **Typical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted

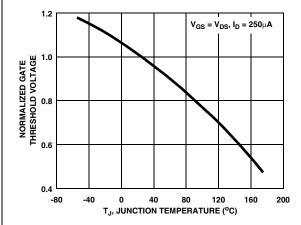


Figure 11. Normalized Gate Threshold Voltage vs Junction Temperature

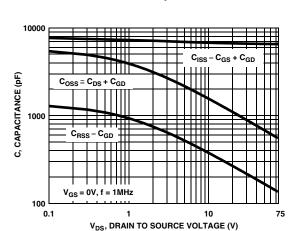


Figure 13. Capacitance vs Drain to Source Voltage

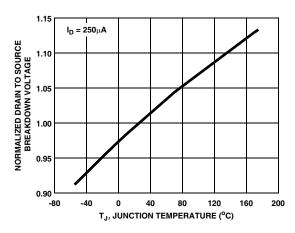


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

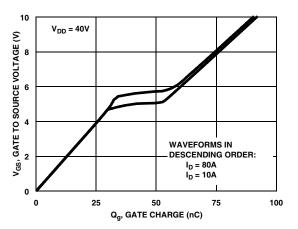


Figure 14. Gate Charge Waveforms for Constant Gate Currents

## **Test Circuits and Waveforms**

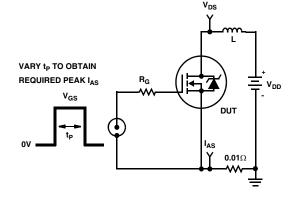


Figure 15. Unclamped Energy Test Circuit

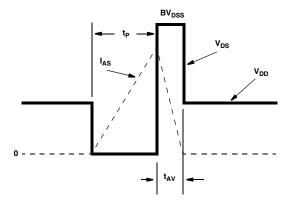


Figure 16. Unclamped Energy Waveforms

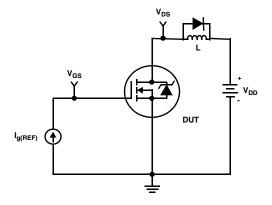


Figure 17. Gate Charge Test Circuit

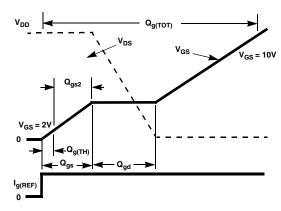


Figure 18. Gate Charge Waveforms

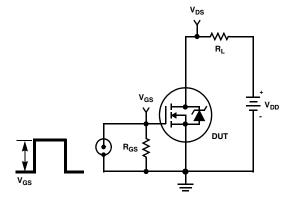


Figure 19. Switching Time Test Circuit

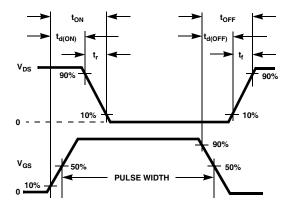


Figure 20. Switching Time Waveforms

## Thermal Resistance vs. Mounting Pad Area

The maximum rated junction temperature,  $T_{JM}$ , and the thermal resistance of the heat dissipating path determines the maximum allowable device power dissipation,  $P_{DM}$ , in an application. Therefore the application's ambient temperature,  $T_A$  (°C), and thermal resistance  $R_{\theta JA}$  (°C/W) must be reviewed to ensure that  $T_{JM}$  is never exceeded. Equation 1 mathematically represents the relationship and serves as the basis for establishing the rating of the part.

$$P_{DM} = \frac{(T_{JM} - T_A)}{R_{\theta, JA}}$$
 (EQ. 1)

In using surface mount devices such as the TO-263 package, the environment in which it is applied will have a significant influence on the part's current and maximum power dissipation ratings. Precise determination of  $P_{DM}$  is complex and influenced by many factors:

- Mounting pad area onto which the device is attached and whether there is copper on one side or both sides of the board.
- The number of copper layers and the thickness of the board.
- 3. The use of external heat sinks.
- 4. The use of thermal vias.
- 5. Air flow and board orientation.
- For non steady state applications, the pulse width, the duty cycle and the transient thermal response of the part, the board and the environment they are in.

Fairchild provides thermal information to assist the designer's preliminary application evaluation. Figure 21 defines the  $R_{\theta JA}$  for the device as a function of the top copper (component side) area. This is for a horizontally positioned FR-4 board with 1oz copper after 1000 seconds of steady state power with no air flow. This graph provides the necessary information for calculation of the steady state junction temperature or power dissipation. Pulse applications can be evaluated using the Fairchild device Spice thermal model or manually utilizing the normalized maximum transient thermal impedance curve.

Thermal resistances corresponding to other copper areas can be obtained from Figure 21 or by calculation using Equation 2 or 3. Equation 2 is used for copper area defined in inches square and equation 3 is for area in centimeters square. The area, in square inches or square centimeters is the top copper area including the gate and source pads.

$$R_{\theta JA} = 26.51 + \frac{19.84}{(0.262 + Area)}$$
 (EQ. 2)

Area in Inches Squared

$$R_{\theta JA} = 26.51 + \frac{128}{(1.69 + Area)}$$
 (EQ. 3)

Area in Centimeter Squared

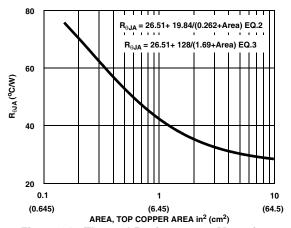
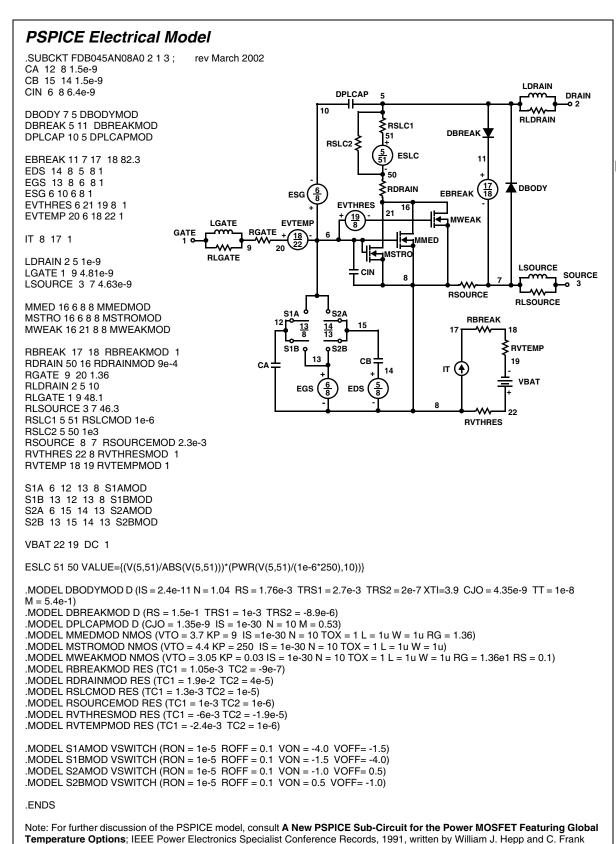


Figure 21. Thermal Resistance vs Mounting Pad Area

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FDB045AN08A0\_F085 Rev. A

Wheatley.

#### SABER Electrical Model REV March 2002 template FDB045AN08A0 n2,n1,n3 electrical n2,n1,n3 var i iscl dp..model dbodymod = (isl = 2.4e-11, n1 = 1.04, rs = 1.76e-3, trs1 = 2.7e-3, trs2 = 2e-7, xti = 3.9, cjo = 4.35e-9, tt = 1e-8, m = 5.4e-1) dp., model dbreakmod = (rs = 1.5e-1, trs1 = 1e-3, trs2 = -8.9e-6)dp..model dplcapmod = (cjo = 1.35e-9, isl =10e-30, nl =10, m = 0.53) m..model mmedmod = $(type=_n, vto = 3.7, kp = 9, is =1e-30, tox=1)$ m..model mstrongmod = (type=\_n, vto = 4.4, kp = 250, is = 1e-30, tox = 1) m..model mweakmod = (type= n, vto = 3.05, kp = 0.03, is = 1e-30, tox = 1, rs=0.1) sw\_vcsp..model s1amod = (ron = 1e-5, roff = 0.1, von = -4.0, voff = -1.5) sw\_vcsp..model s1bmod = (ron =1e-5, roff = 0.1, von = -1.5, voff = -4.0) sw\_vcsp..model s2amod = (ron = 1e-5, roff = 0.1, von = -1.0, voff = 0.5) sw\_vcsp..model s2bmod = (ron = 1e-5, roff = 0.1, von = 0.5, voff = -1.0) LDRAIN DPLCAP DRAIN 10 c.ca n12 n8 = 1.5e-9RLDRAIN c.cb n15 n14 = 1.5e-9 RSLC1 c.cin n6 n8 = 6.4e-9RSLC2 ISCI dp.dbody n7 n5 = model=dbodymod dp.dbreak n5 n11 = model=dbreakmod DBREAK 3 50 dp.dplcap n10 n5 = model=dplcapmod RDRAIN 8 ESG 11 i.it n8 n17 = 1DBODY **EVTHRES** (<u>19</u>) MWEAK **LGATE EVTEMP** I.ldrain n2 n5 = 1e-9RGATE 18 22 I.lgate n1 n9 = 4.81e-9**EBREAK ←**MMED 20 I.Isource n3 n7 = 4.63e-9MSTRO RLGATE **LSOURCE** m.mmed n16 n6 n8 n8 = model=mmedmod, l=1u, w=1uCIN SOURCE m.mstrong n16 n6 n8 n8 = model=mstrongmod, l=1u, w=1u m.mweak n16 n21 n8 n8 = model=mweakmod, l=1u, w=1u **RSOURCE** RLSOURCE S1A res.rbreak n17 n18 = 1, tc1 = 1.05e-3, tc2 = -9e-7 RBREAK <u>13</u> 8 res.rdrain n50 n16 = 9e-4, tc1 = 1.9e-2, tc2 = 4e-517 res.rgate n9 n20 = 1.36 **₹**RVTEMP S<sub>1</sub>B o S2B res.rldrain n2 n5 = 10 СВ 19 res.rlgate n1 n9 = 48.1CA IT 14 res.rlsource n3 n7 = 46.3 VBAT res.rslc1 n5 n51= 1e-6, tc1 = 1e-3, tc2 =1e-5 8 EGS res.rslc2 n5 n50 = 1e3 res.rsource n8 n7 = 2.3e-3. tc1 = 1e-3. tc2 =1e-6 res.rvtemp n18 n19 = 1, tc1 = -2.4e-3, tc2 = 1e-6 **RVTHRES** res.rvthres n22 n8 = 1, tc1 = -6e-3, tc2 = -1.9e-5 spe.ebreak n11 n7 n17 n18 = 82.3 $^{.}$ spe.eds n14 n8 n5 n8 = 1 spe.eqs n13 n8 n6 n8 = 1spe.esg n6 n10 n6 n8 = 1 spe.evtemp n20 n6 n18 n22 = 1 spe.evthres n6 n21 n19 n8 = 1 sw\_vcsp.s1a n6 n12 n13 n8 = model=s1amod sw\_vcsp.s1b n13 n12 n13 n8 = model=s1bmod sw\_vcsp.s2a n6 n15 n14 n13 = model=s2amod sw\_vcsp.s2b n13 n15 n14 n13 = model=s2bmod v.vbat n22 n19 = dc=1 equations { i(n51->n50) +=iscliscl: v(n51,n50) = ((v(n5,n51)/(1e-9+abs(v(n5,n51))))\*((abs(v(n5,n51)\*1e6/250))\*\*10))

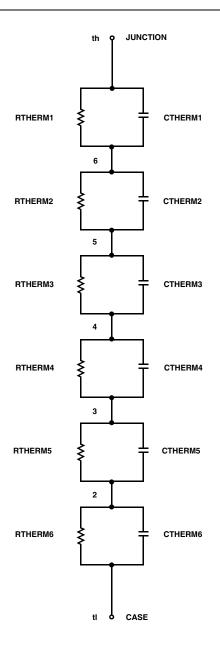
# SPICE Thermal Model REV 23 March 2002 FDB045AN08A0T

CTHERM1 th 6 6.45e-3 CTHERM2 6 5 3e-2 CTHERM3 5 4 1.4e-2 CTHERM4 4 3 1.65e-2 CTHERM5 3 2 4.85e-2 CTHERM6 2 tl 1e-1 RTHERM1 th 6 3.24e-3 RTHERM2 6 5 8.08e-3 RTHERM3 5 4 2.28e-2 RTHERM4 4 3 1e-1 RTHERM5 3 2 1.1e-1

RTHERM6 2 tl 1.4e-1

## SABER Thermal Model

SABER thermal model FDB045AN08A0T template thermal\_model th tl thermal\_c th, tl { therm.ctherm1 th 6=6.45e-3 ctherm.ctherm2 6.5=3e-2 ctherm.ctherm3 5.4=1.4e-2 ctherm.ctherm4 4.3=1.65e-2 ctherm.ctherm5 3.2=4.85e-2 ctherm.ctherm6 2.tl=1e-1 rtherm.rtherm1 th 6=3.24e-3 rtherm.rtherm2 6.5=8.08e-3 rtherm.rtherm3 5.4=2.28e-2 rtherm.rtherm4 4.3=1e-1 rtherm.rtherm5 3.2=1.1e-1 rtherm.rtherm6 2.tl=1.4e-1







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SuperSOT™-6 SuperSOT™-8 . SupreMOS™ SyncFET™ Sync-Lock™

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